REMARKS

Reconsideration of this application is respectfully requested in view of the following remarks.

Claims 1-9 are currently pending, of which Claims 1 and 5 are independent claims. No amendments have made herein.

In the Office Action mailed on August 6, 2007, claims 1-5 and 9 were rejected under 35 U.S.C. §103(a) as being unpatentable over Japanese Patent No. JP10074962 to Honbo ("Honbo") in view of U.S. Patent No. 4809054 to Waldner ("Waldner"). Claim 6 was rejected under 35 U.S.C. 103(a) as being unpatentable over Honbo in view of Waldner as applied to claim 5, and further in view of U.S. Patent Publication No. 2003/0121437 to Nishimura ("Nishimura"). Claim 7 was rejected under 35 U.S.C. 103(a) as being unpatentable over Honbo in view of Waldner as applied to claim 5, and further in view of U.S. Patent No. 5,679,975 to Wyland et al. ("Wyland"). Finally, Claim 8 was rejected under 35 U.S.C. 103(a) as being unpatentable over Honbo in view of Waldner as applied to claim 5, and further in view of U.S. Patent No. 6,885,016 to Worley et al. ("Worley"). Applicants respectfully traverse the above rejection, as follows:

Claim 1 recites a leadframe comprising an element mount frame, a fitting frame that is laid beside the element mount frame with a gap left in between, and a shielding frame that is tied via a tying portion to the fitting frame and that can be brought into such a state as to cover the element mount frame by bending the tying portion, wherein the fitting frame is positioned between the shielding frame and the element mount frame, wherein a photodetector element having a light receiving portion is mounted on the element mount frame, and wherein the shielding frame has a window such that when

the shielding frame covers the element mount frame, the window overlaps the light-receiving portion of the photodetector element, thereby permitting light to strike the photodetector element.

A photodetector module recited in Claim 5 comprises a photodetector element having a light-receiving portion, an element mount frame on which the photodetector element is mounted, a fitting frame that is laid beside the element mount frame with a gap left in between, a shielding frame that is tied via a tying portion to the fitting frame and that can be brought into such a state as to cover the element mount frame by bending the tying portion, and molding resin in which the element mount frame and the fitting frame are sealed, wherein the fitting frame is positioned between the shielding frame and the element mount frame, and wherein the shielding frame has a window such that when the shielding frame covers the element mount frame, the window overlaps the light-receiving portion of the photodetector element, thereby permitting light to strike the photodetector element.

Honbo describes a infrared remote control light-receiving unit, which, as shown in Fig. 2, comprises a mold portion 11 and a non-mold portion 12. The mold portion 11 has a light-receiving element 13 and is connected with the non-mold portion 12 via a bending section 20a. The non-mold portion 12 has a hole 21 in a position so that when the non-mold portion 12 is folded above the mold portion 11, the light-receiving element 13 is exposed from the hole 21.

Clearly, as admitted by the Examiner, Honbo fails to disclose a fitting frame that is laid beside the element mount frame (i.e., molded portion 11) with a gap left in

between, and which is positioned between the shielding frame (i.e., non-molded portion 12) and the element mount frame, as recited in Claims 1 and 5.

Waldner, on the other hand, has connecting bar member 28 connecting pad 16 to an adjacent cross strip 22. The connecting bar member 28 is formed of two parallel legs 34 that each connects with the pad 16 on one end and connects with a bar 30 at the other end. In col. 3, lines 4-21, Waldner describes that the pair of legs 34 are adapted to be bent intermediate their ends through an angle of about 180 °C or until the legs are doubled upon themselves to cause the pad 16 to be in overlying spaced relationship to the respective pad 14 as shown in Figs. 3 and 4.

The Examiner alleged that the bar 30 corresponds to the fitting member of amended Claims 1 and 5. Applicants respectfully disagree. Indeed, the bar 30 is not positioned between a shielding frame and the element mount frame. The Examiner seems to think that the pad 16 is a shielding frame and the pad 14 is an element mount frame. However, from the description of col. 3, lines 35-40 and 50-58 of Waldner, both of the pads 14 and 16 are provided at their upper surfaces with coating 39 and 41 of solder and the pad 16 receives a semiconductor chip 44 that is placed on a rosin layer of the pad 16. From this description, the pad 16 should be considered as an element mount frame on which an electronic element is mounted. However, the pad 14 is neither an element mount frame nor a shielding frame because it is coated with solder that is adapted to contact with the semiconductor chip 44 when the pad 16 is bent over to overlap the pad 14 (See Waldner, col. 4, lines 7-11 and Figs. 2-3,) and does not include a window. Therefore, the bar 30 is not a fitting frame of Claims 1 and 15 and Waldner does not disclose a shielding member that is tied via a tying portion to the

fitting frame (not shown in Waldner) by bending the typing portion and has a window such that when the shielding frame covers the element mount frame, the window overlaps the light-receiving portion of the photoelectron element, as recited in Claim 1. Furthermore, Waldner does not disclose a fitting member, that is positioned between the shielding frame (not disclosed in Waldner) and the element mount frame (e.g., element 16,) as recited in Claim 1.

Accordingly, neither Honbo nor Waldner, when taken singly or in combination, teaches or suggests all of the elements recited in Claims 1 and 5, specifically the fitting frame and the shielding frame and their connections with the element mount frame. It has, thereof, not been obvious for one skilled in the art to combine Honbo and Waldner to achieve the leadframe of Claim 1 and the photodetector module of Claim 5.

Accordingly, Applicants respectfully submit that Claims 1-5 and 9 should be patentable over Honbo in view of Waldner.

None of Nishirmura, Wyland, or Worley cure the above deficiencies of Honbo and Waldner. At least due to their dependencies from patentable independent Claims 1 and 5 and the reasons set forth, Claims 6-8 should be also patentable over Honbo in view Waldner, and further in view of either one of Nishimura, Wyland, and Worley.

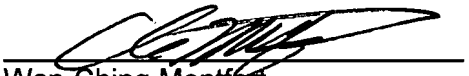
Conclusion

For all of the above reasons, it is respectfully submitted that claims 1-9 are in condition for allowance and a Notice of Allowability is earnestly solicited.

Should the Examiner determine that any further action is necessary to place this application into better form the Examiner is invited to contact the undersigned representative at the telephone number listed below.

In the event this paper is not considered to be timely filed, the Applicants hereby petition for an appropriate extension of time. The Commissioner is hereby authorized to charge any fee deficiency or credit any overpayment associated with this communication to Deposit Account No. 01-2300 referencing client matter number **103213-00105**.

Respectfully submitted,



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